



Product Change Notification

Change Notification #: 117191 - 00
Change Title: Select Intel® Optane™ SSD 905P Series, PCN 117191-00, Product Material, Documentation, Addition of Thermal solution and assembly guide
Date of Publication: October 08, 2019

Key Characteristics of the Change:

Product Material, Documentation

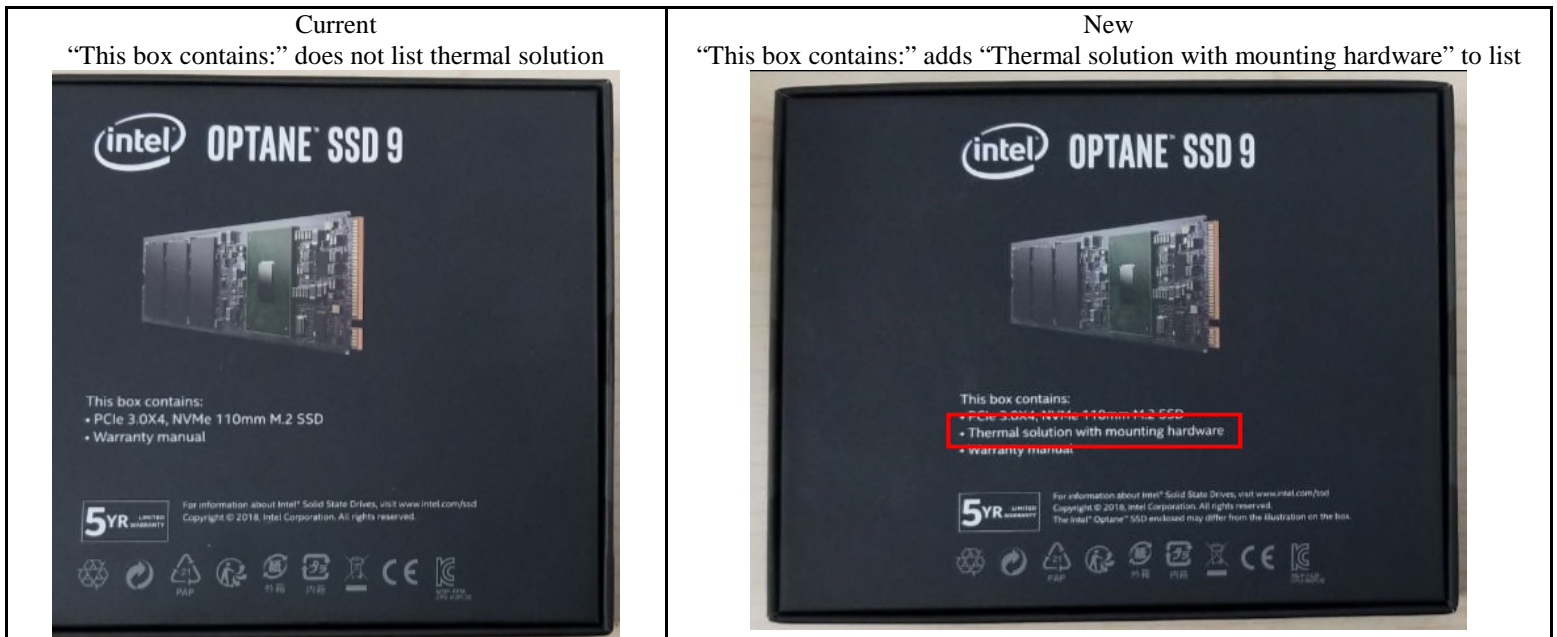
Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	November 1, 2019
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Description of Change to the Customer:

The Intel® Optane™ SSD 905P Series SKU listed in the Product/s Affected Table below will have the following changes.

- Adding a Thermal solution with mounting Hardware.
- Changes were made to the artwork of the retail box to include the addition of the thermal solution.



Thermal solution installation instructions



Thermal solution assembly



Customer Impact of Change and Recommended Action:

This change has been thoroughly evaluated to ensure that there are no quality, reliability or functional implications to our customers. Intel is not recommending additional qualification of these changes on platforms received from Intel.

No change to form fit or function. No change to Intel Ordering codes.

Customers who have purchased this product previously and did not have a thermal solution assembly in the retail box, can contact ICS and request one if needed by visiting www.intel.com/ssdmodulesupport

Milestone dates are estimates and subject to change based on business and operational conditions.

Products Affected / Intel Ordering Codes:

Marketing Name	Product Code	MM#
Solid State Drive 380 GB PCIe M.2 110MM Retail Box 1pk	SSDPEL1D380GAX1	978082

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
October 8, 2019	00	Originally Published PCN



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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com

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